TOSHIBA CORPORATION
Toshiba Electronic Devices & Storage Corporation

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Date: September 17, 2026
Ref. No.: DO2026-00004E-H1

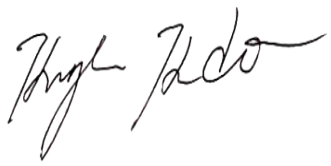
To. TTI INC.

Dear Sir/ Madam:

Notice of change in packing material (cover tape)

We greatly appreciate your continued business.
This is to notify our customers of our plan to change the cover tape used in the packing materials of our products supplied to you.
Full details of the planned change are given in the following page.
If you have any questions or inquiries regarding this change, please contact your nearest Sales representative as soon as possible.
We appreciate your understanding and cooperation.

Yours faithfully,
Reviewed by H. Kashima
Approved by K.Kudo, Manager



Quality & Reliability Service Group
Semiconductor Quality Center Semiconductor Quality & Reliability Engineering Dept.
Toshiba Electronic Devices & Storage Corporation

Notice of change in packing material (cover tape)

1. Product to be Affected	:	39 Target Products (See Attached List)
2. Description of Change	:	Target part: Cover tape material manufacturer Company A→ Company B
3. Reason of Change	:	Because the cover tape material manufacturer has gone bankrupt, we will change the new material manufacturer. The new manufacturer has a long track record of use with our outsourcing partner.
4. Scheduled Date of Change	:	**From early December 2026** (Timing may vary depending on inventory of current materials.)
5. Other information	:	There will be no changes to any materials (other than the cover tape), personnel, equipment, processes, or the operational environment (factory). The transmittance and haze values of the cover tape show slight differences compared with the current product. We have confirmed from our internal evaluation that there are no issues. **After late November 2026** has passed, we will proceed with the change as planned.
6. Remark	:	If you have any questions or requests regarding this change, please inform our Sales representatives nearest you as soon as possible.

No. DO2026-00004E-H01

Notice of change in packaging material (cover tape)

TOSHIBA

September 17, 2026
Quality & Reliability Engineering Dept.,Oita Office
Semiconductor Quality Center
Toshiba Electronic Devices & Storage Corporation

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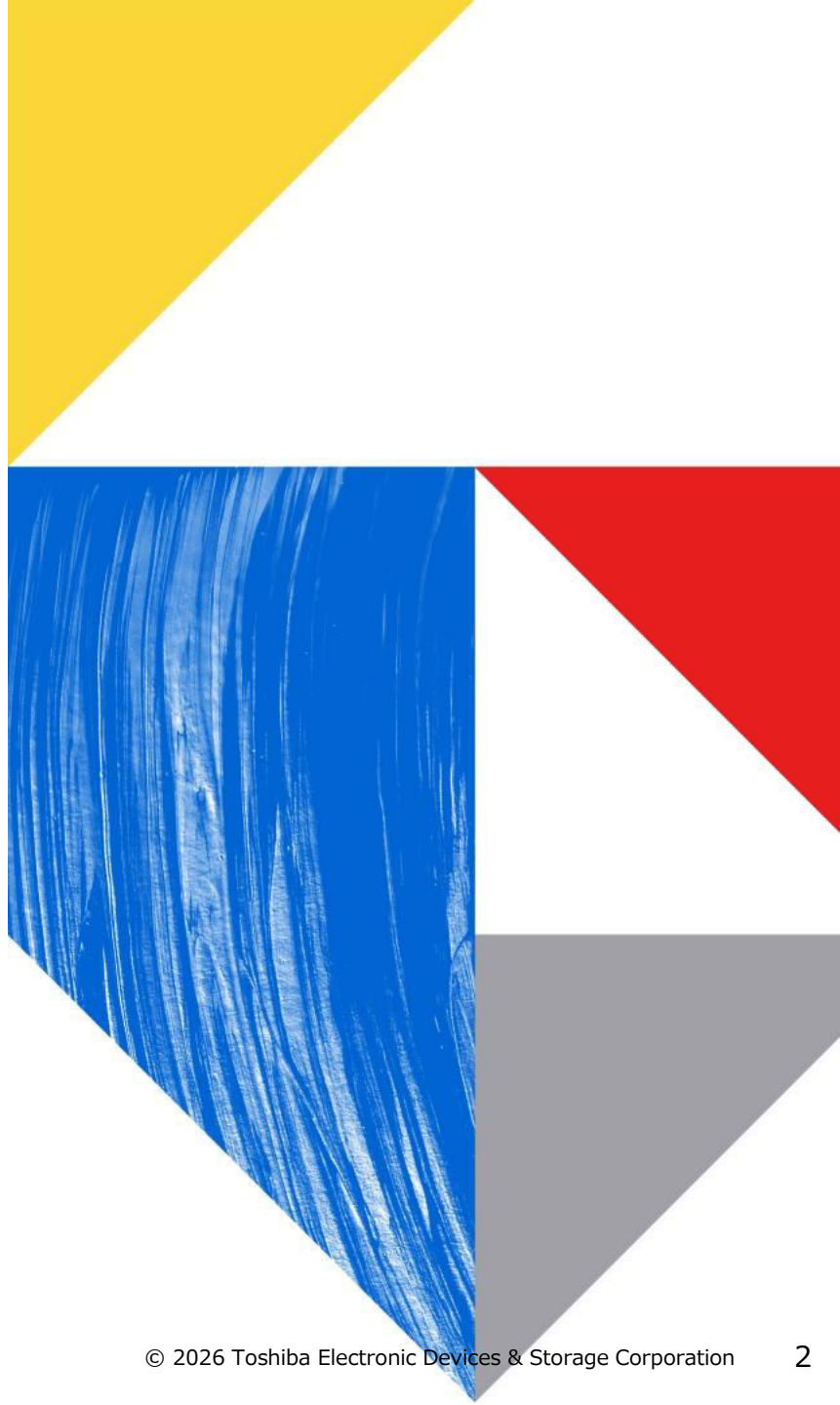
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Overview of Changes



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1. Overview of Changes

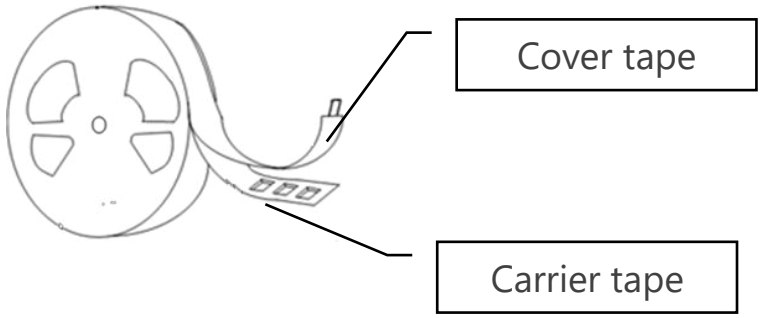
◆ Background/reason

The material manufacturer of the cover tape currently in use has gone bankrupt and is no longer able to supply the material. Therefore, in order to ensure a stable supply, we would like to change the cover tape. We kindly ask for your approval and appreciate your understanding and cooperation.

◆ Changed member

Cover tape : 13.3 / 21.0 mm width

	Current	Change
Cover tape manufacturer	Company A	Company B
Main material	PET	PE



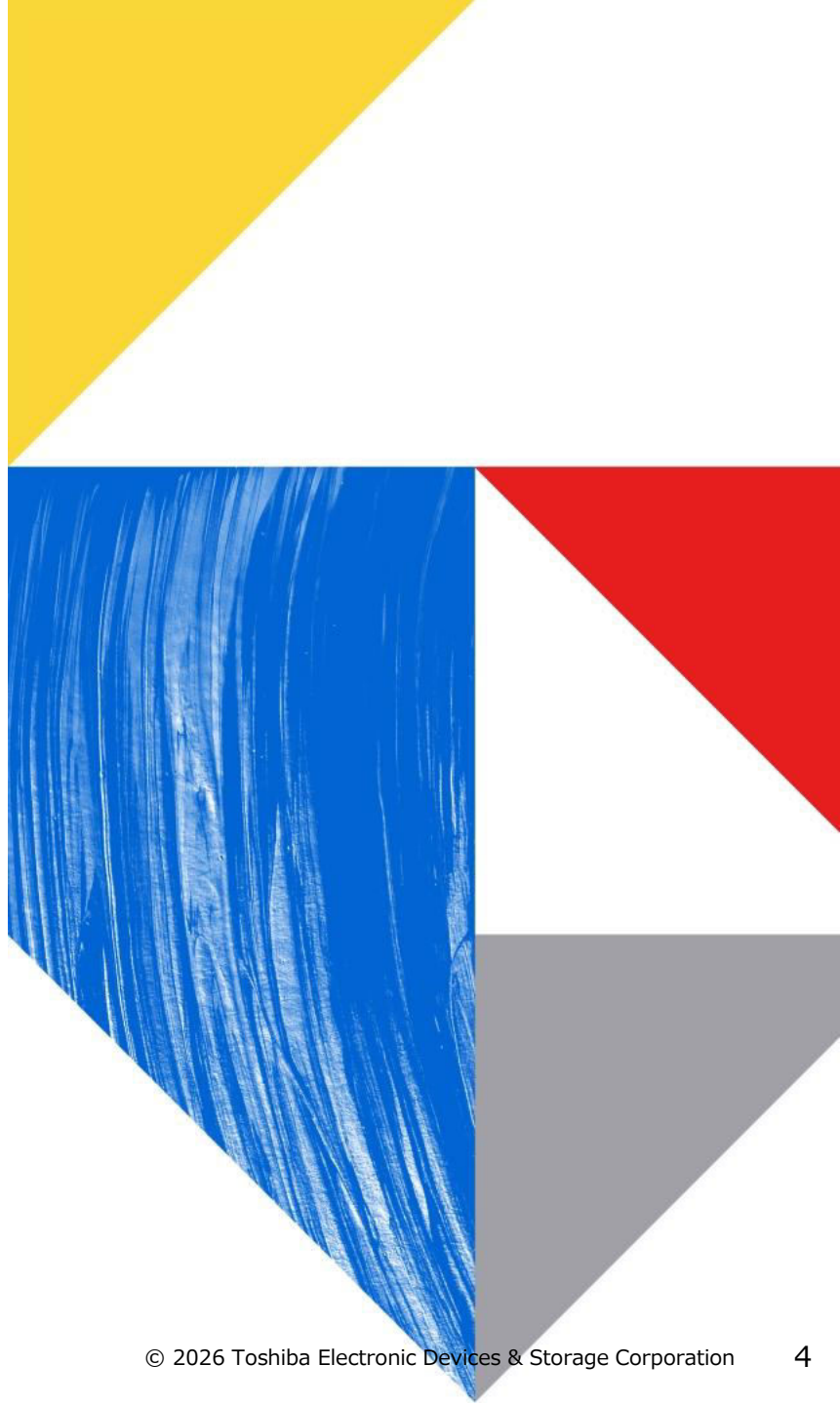
◆ Applicable products

See attached document.

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02

Changes



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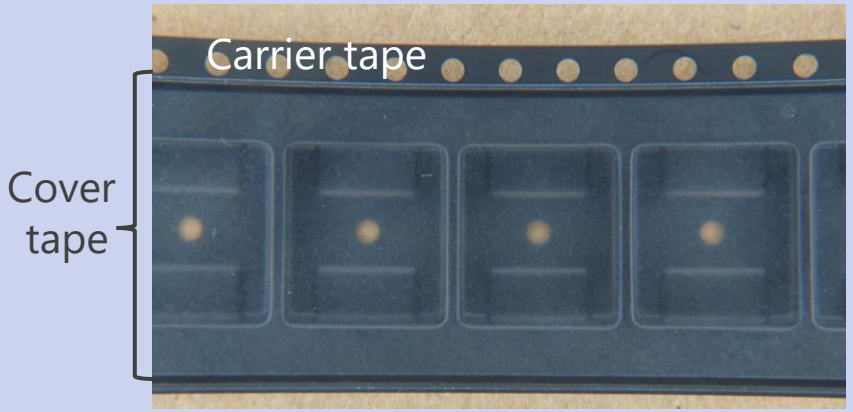
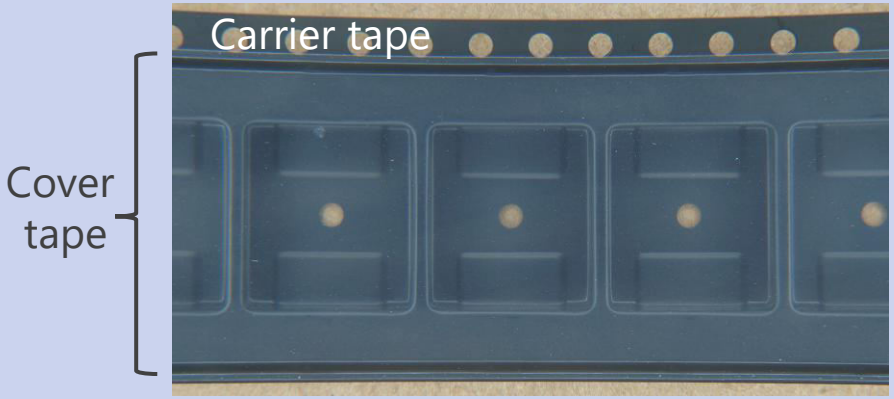
2. Changes : 5M1E

5M1E	Changes	Changed/Unchanged
Man	–	Unchanged
Machine	–	Unchanged
Material	**・Cover Tape Manufacturer Company A → Company B ・Main Material PET → PE**	**Changed**
Method	–	Unchanged
Measurement	–	Unchanged
Environment	–	Unchanged

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2. Changes : Details of the change

◆Change point: Change details

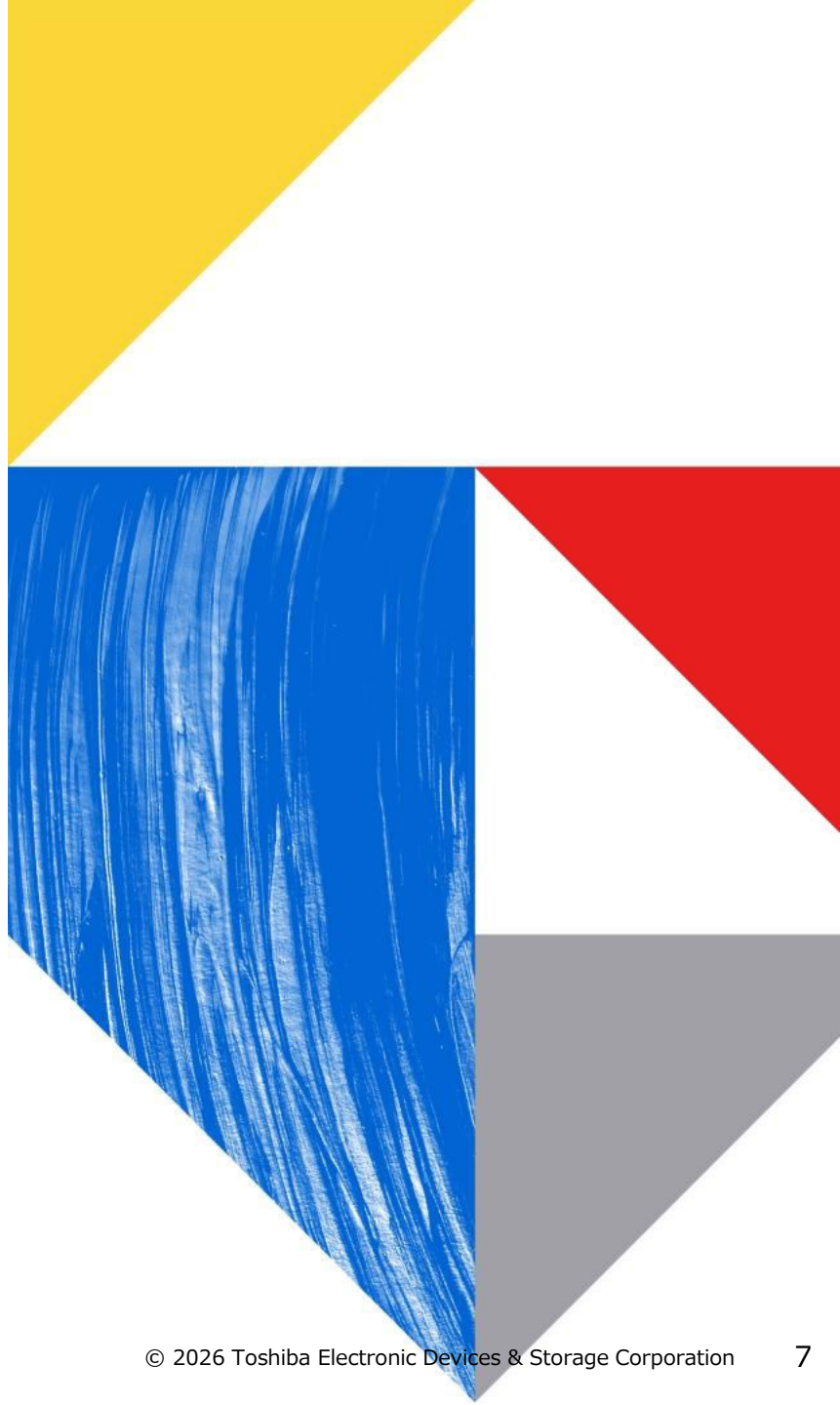
item	Current product	Changed product
Cover tape manufacturer	Company A	Company B
Main material	PET	PE
Transmittance	≧90%	88%
Haze	≦45%	11%
Appearance		

We have confirmed that the visibility is equivalent.

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03

Risk analysis for changes



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3. Risk analysis for changes

Change point	Function	Failure mode	Cause / factor of failure	Potential Effect(s) of Failure	What design measures were taken to eliminate the failure	Items that should be reflected in the evaluation indicated by DRBFM	Evaluation quantity
Cover tape	Protects ICs from popping out of the carrier tape	Lead deformation	Weak adhesion causes the cover tape to peel off	Mounting defect	Maintain seal peel strength within specifications	Seal peel strength	1 p
		Electrical characteristic	High surface resistivity may cause ESD damage to ICs	Performance defect	Apply materials with surface resistivity within the required standard	Surface resistivity	5p

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Content of Evaluation

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4. Content of Evaluation : Identification of assessment items by risk analysis

Evaluation Item	Quantity	Acceptance Criteria	Remarks
Seal Peeling Strength	1pcs	0.1～1.3N	Strength compliant with the EIA-481 standard
Surface Resistance	5pcs	1×10^{4}～1×10^{11} Ohms	Resistance compliant with the ANSI/ESD S20.20 standard

We are extracting evaluation items from the risk analysis.

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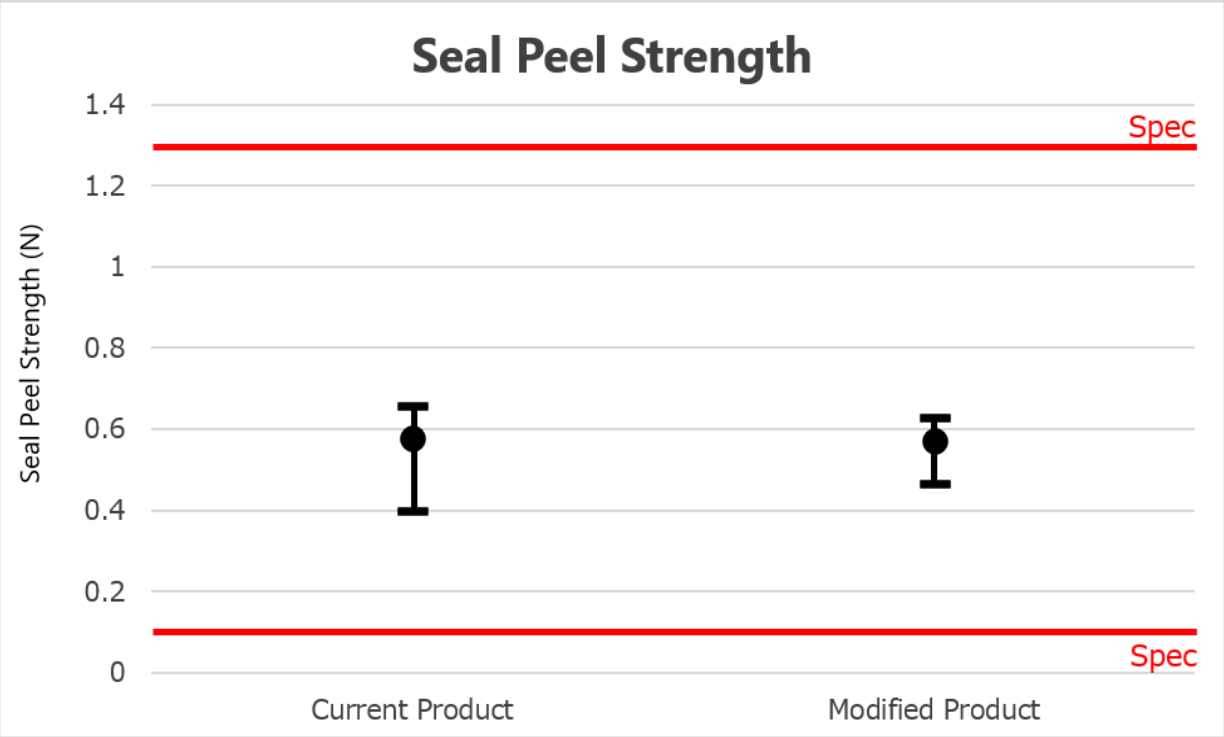
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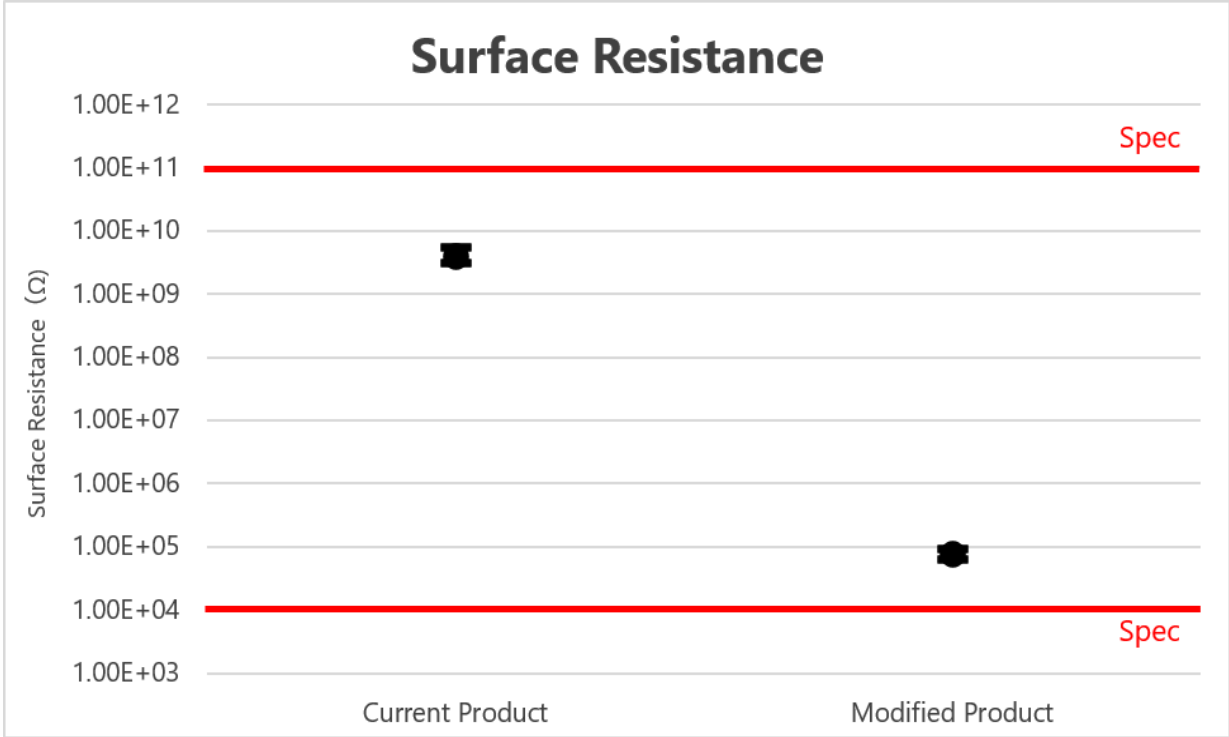
Evaluation Results

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5. Evaluation 13.3mm Width

Evaluation Item	Quantity	Acceptance Criteria	Judgment Result
Seal Peel Strength	1pcs	0.1～1.3N	Pass
Surface Resistance	5pcs	1×10^{4}～1×10^{11} Ω	Pass



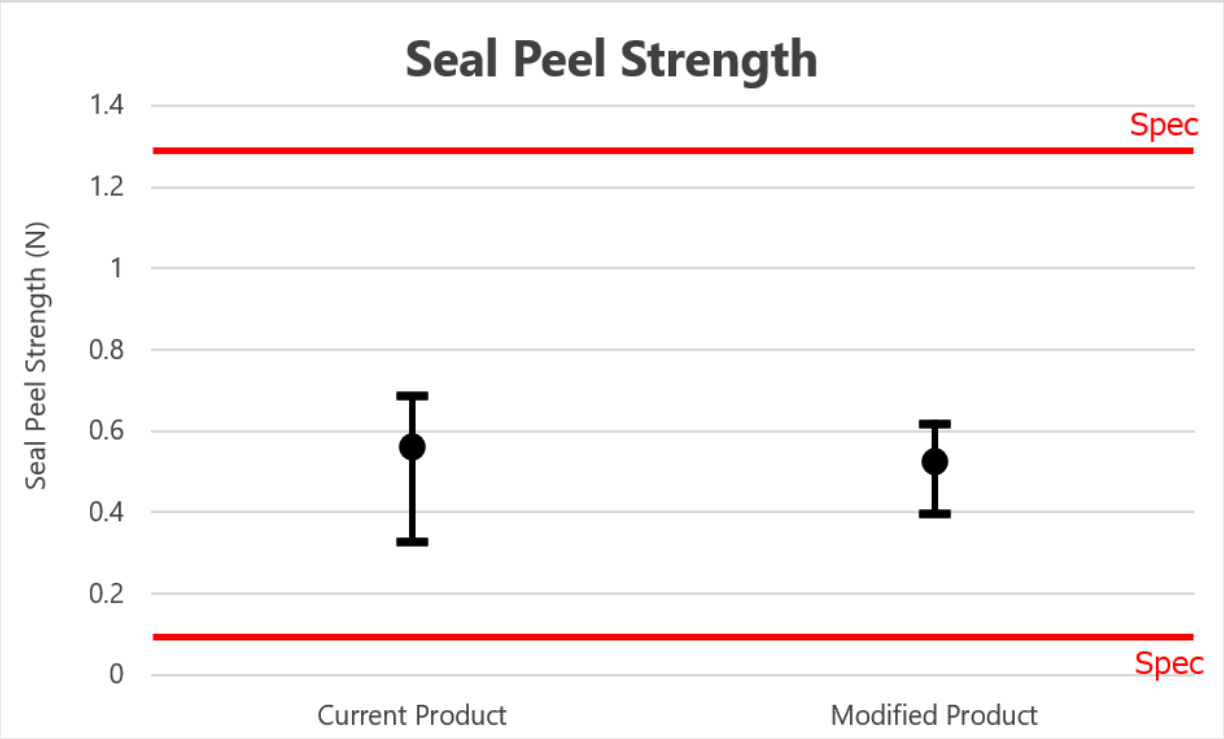


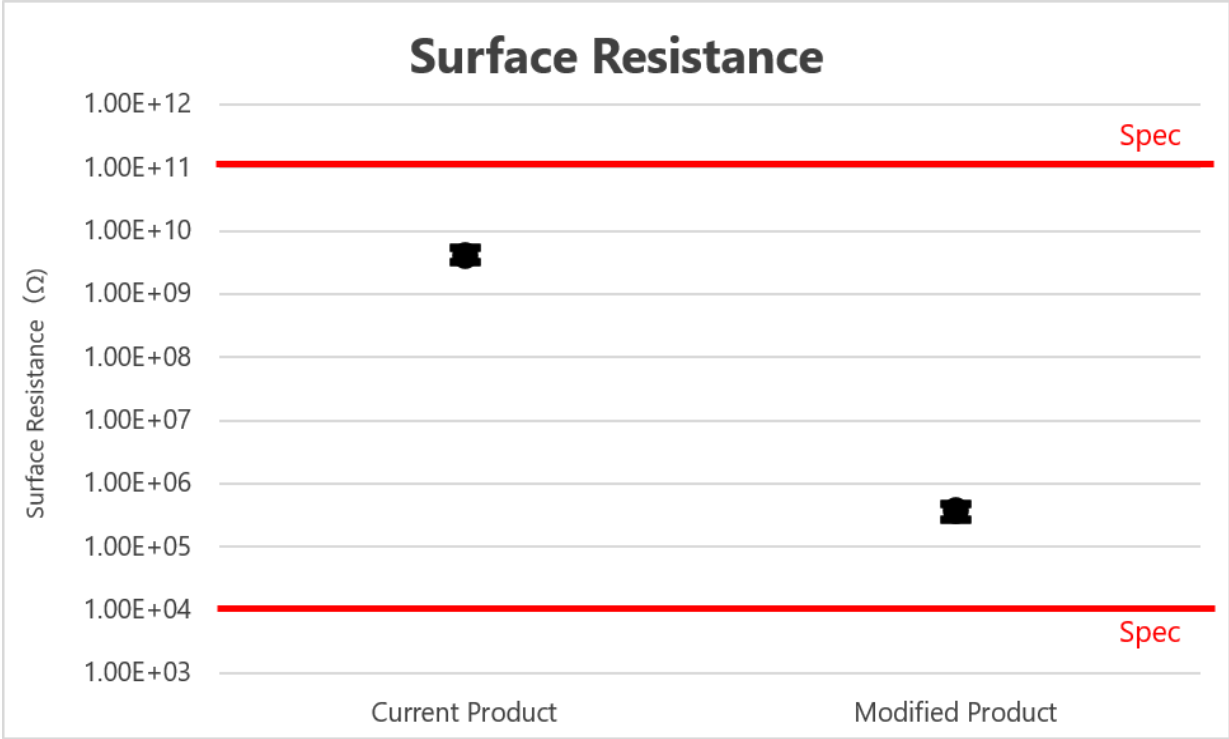
We have confirmed that all evaluation results are within the specified standards.

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5. Evaluation 21.0mm Width

Evaluation Item	Quantity	Acceptance Criteria	Judgment Result
Seal Peel Strength	1pcs	0.1～1.3N	Pass
Surface Resistance	5pcs	1×10^{4}～1×10^{11} Ω	Pass





We have confirmed that all evaluation results are within the specified standards.

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Schedule

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6. Schedule

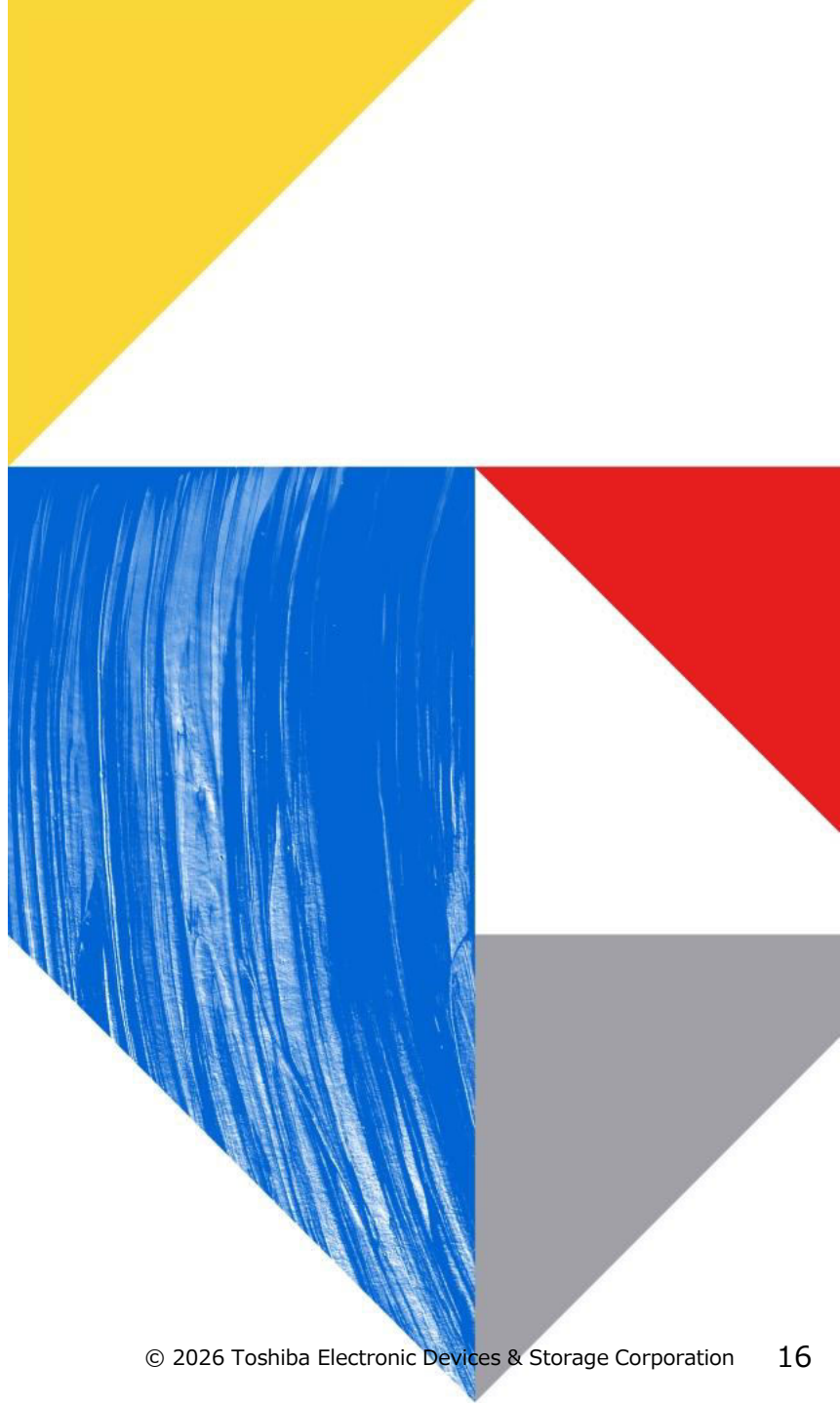


We plan to switch to mass production sequentially as the inventory of the current product is depleted.

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The END



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